



HPMC-124-04-L-D-04

HPFC-114-02-L-D-02

(2,54 mm) .100"

HPFC, HPMC SERIES

SIGNAL POWER COMBO SYSTEM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPFC or www.samtec.com?HPMC

Insulator Material:
Black Liquid Crystal Polymer
Signal Contact (HPFC):
Phosphor Bronze
Power Contact (HPFC):
BeCu
Terminal (HPMC):
Phosphor Bronze (Signal & Power)
Plating:
Sn or Au over 50µ" (1,27 µm)
Ni on signal pins; Sn over 50µ" (1,27 µm) Ni on power pins
Operating Temp Range:
-55°C to +105°C with Tin;
-55°C to +125°C with Gold
Contact Resistance:
10 mΩ
Insertion Depth:
(3,68 mm) .145" to
(8,26 mm) .325"
Wiping Distance:
(0,381 mm) .015"
Insertion Force:
(Single contact only)
5 oz (1,39 N) avg. (signal pins)
56 oz (15,57 N) avg. (power pins)
Withdrawal Force:
(Single contact only)
3 oz (0,83 N) avg. (signal pins)
52 oz (14,46 N) avg. (power pins)
Voltage Rating:
850 VAC/1201 VDC
RoHS Compliant:
Yes

Processing:
Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0,15 mm) .006" max (02-20)
(0,20 mm) .008" max (21-24)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note:
Some lengths, styles and options are non-standard, non-returnable.

HPFC	1	SIGNAL PIN PER ROW	LEAD STYLE	SIGNAL PIN PLATING	D	POWER PINS	OPTION
Mates with: HPMC		02 thru 24	-01 = Through-Hole -02 = Surface Mount	-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on tail (Power Pins = All Matte Tin) -T = Matte Tin		02 thru 04	-LC = Locking Clip (Manual placement required) (Not available with -01 lead style) -K = (6,50 mm) .256" DIA Polyimide film Pick & Place Pad (5 positions minimum)

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• Locking clip option

HPMC	1	SIGNAL PIN PER ROW	LEAD STYLE	SIGNAL PIN PLATING	D	POWER PINS
Mates with: HPFC		02 thru 24	Specify LEAD STYLE from chart	-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on tail (Power Pins = All Matte Tin) -T = Matte Tin		02 thru 04

LEAD STYLE	A
-01, -02	(5,84) .230
-03, -04	(8,13) .320